



Docket No.: 008063 USA MTCG/PINTGR

PATENT/OFFICIAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



In re Application of

Deenesh PADHI et al.

Serial No. 10/812,480

Filed: March 30, 2004

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: Group Art Unit:
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: Examiner:

For: SELECTIVE METAL ENCAPSULATION SCHEMES

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

The references listed on Sheet 1 of the attached PTO-1449 Forms were cited in a patentability investigation and/or a corresponding foreign or PCT application relating to the above-referenced application. The remaining references are from potentially related patent applications, and possibly other sources.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

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Date: 6/16/04

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				FILING DATE March 30, 2004		GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	3,205,485	09/07/65	Noltingk			10/21/60	
	3,229,198	01/11/66	Libby			09/28/62	
	3,767,900	10/23/73	Chao et al.			06/23/71	
	3,920,965	11/18/75	Sohrwardy			03/04/74	
	4,000,458	12/28/76	Miller et al.			08/21/75	
	4,207,520	06/10/80	Flora et al.			04/06/78	
	4,209,744	06/24/80	Gerasimov et al.			03/27/78	
	4,302,721	11/24/81	Urbanek et al.			05/15/79	
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	4,967,381	10/30/90	Lane et al.			07/06/89	
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	5,260,868	11/09/93	Gupta et al.			10/15/91	
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	5,283,141	02/01/94	Yoon et al.			03/05/92			
	5,295,242	03/15/94	Mashruwala et al.			11/02/90			
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	5,642,296	06/24/97	Saxena			07/29/93	
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	5,665,199	09/09/97	Sahota et al.			06/23/95	
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	5,751,582	05/12/98	Saxena et al.			09/24/96	
	5,754,297	05/19/98	Nulman			04/14/97	
	5,761,064	06/02/98	La et al.			10/06/95	
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	5,787,021	07/28/98	Samaha			12/18/95	
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	5,812,407	09/22/98	Sato et al.			08/12/97	
	5,823,854	10/20/98	Chen			05/28/96	
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	5,923,553	07/13/99	Yi			10/05/96	
	5,926,690	07/20/99	Toprac et al.			05/28/97	
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	5,940,300	08/17/99	Ozaki			05/08/97	
	5,943,237	08/24/99	Van Boxem			10/17/97	
	5,960,185	09/28/99	Nguyen			06/24/96	
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96	
	5,961,369	10/05/99	Bartels et al.			06/04/98	
	5,963,881	10/05/99	Kahn et al.			10/20/97	
	5,978,751	11/02/99	Pence et al.			02/25/97	
	5,982,920	11/09/99	Tobin, Jr. et al.			01/08/97	
	6,002,989	12/14/99	Shiba et al.			04/01/97	
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	6,054,379	04/25/00	Yau et al.			02/11/98	
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	6,072,313	06/06/00	Li et al.			06/17/97	
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	6,077,412	06/20/00	Ting et al.			10/30/98	
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	6,097,887	08/01/00	Hardikar et al.			10/27/97	
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	6,112,130	08/29/00	Fukuda et al.			10/01/97	
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	6,127,263	10/03/00	Parikh			07/10/98	
	6,128,016	10/03/00	Coelho et al.			12/20/96	
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	6,141,660	10/31/00	Bach et al.			07/16/98	
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	6,159,644	12/12/00	Satoh et al.			03/06/96	
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				APPLICANT Deenesh PADHI et al.			
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	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques					
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium					
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System					
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder					
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers					
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service					
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems					
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide					
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow					
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes					
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	09/928,474	08/14/01	Krishnamurthy et al.	Experiment Management System, Method and Medium					
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	09/943,955	08/31/01	Shanmugasundram et al.	Feedback Control of a Chemical Mechanical Polishing Device Providing Manipulation of Removal Rate Profiles					
	09/998,372	11/30/01	Paik	Control of Chemical Mechanical Polishing Pad Conditioner Directional Velocity to Improve Pad Life					
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	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control			
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing			
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
	10/173,108	06/18/02	Shanmugasundram et al.	Integrating Tool, Module, and Fab Level Control			
	10/174,370	06/18/02	Shanmugasundram et al.	Feedback Control of Plasma-Enhanced Chemical Vapor Deposition Processes			
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	10/377,654	03/04/03	Kokotov et al.	Method, System and Medium for Controlling Manufacturing Process Using Adaptive Models Based on Empirical Data			
	10/393,531	03/21/03	Shanmugasundram et al.	Copper Wiring Module Control			
	10/632,107	08/01/03	Schwarm et al.	Method, System, and Medium for Handling Misrepresentative Metrology Data Within an Advanced Process Control System			
	10/665,165	09/18/03	Paik	Feedback Control of a Chemical Mechanical Polishing Process for Multi-Layered Films			
	10/712,273	11/14/03	Kokotov	Method, System and Medium for Controlling Manufacture Process Having Multivariate Input Parameters			
	10/759,108	01/20/04	Schwarm	Automated Design and Execution of Experiments with Integrated Model Creation for Semiconductor Manufacturing Tools			
	10/765,921	01/29/04	Schwarm	System, Method, and Medium for Monitoring Performance of an Advanced Process Control System			
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	10/809,906	03/26/04	Surana et al.	A Technique for Process-Qualifying a Semiconductor Manufacturing Tool Using Metrology Data			
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						Yes	No
	EP 0 869 652 A2	10/07/98	Europe			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 877 308 A2	11/11/98	Europe			X	
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	WO 99/09371	02/25/99	WO			X	
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	EP 0 910 123 A1	04/21/99	Europe			X	
	11-126816	05/11/99	Japan			X	
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	EP 0 932 194 A1	07/28/99	Europe			X	
	WO 99/59200	11/18/99	WO			X	
	WO 00/00874	01/06/00	WO			X	
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	EP 1 066 925 A2	01/10/01	Europe			X	
	EP 1 067 757 A1	01/10/01	Europe			X	
	EP 1 071 128 A2	01/24/01	Europe			X	
	WO 01/11679 A1	02/15/01	WO			X	
	WO 01/15865 A1	03/08/01	WO			X	
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	61-66104	04/04/86	Japan			X	
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	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
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	3-202710	09/04/91	Japan			X	
	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
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	08-304023	11/22/96	Japan			X	
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						Yes	No
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